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(54) **RADIATOR**

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(57) **ABSTRACT**

A radiator with high-temperature performance includes a radiating pipe, a heat conducting pipe, an aluminum radiating plate, a main radiating part, and an auxiliary radiating part. The radiating pipe comprises a first end in contact with a heat-generating chip, and a second end. The heat conducting pipe is arranged on both sides of the first end of the heat radiating pipe. The first end and the heat conducting pipe are nested in the aluminum radiating plate. The first heat sink is arranged on the side of the heat dissipation pipe away from the chip. The auxiliary heat dissipation part is connected with the second end. The radiator disclosed improves all-round heat dissipation efficiency and meets the heat dissipation requirements of higher chip power through the heat conduction pipe arranged on the side of the heat dissipation pipe.

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